

To: \_\_\_\_\_

**Change Notification: Photocoupler (Quantity of Inner Carton)**

We appreciate your continuous patronage of our semiconductor products.  
 Change is planned for the following product. Please refer to the following contents.  
 We would appreciate your understanding.

**1. Products affected : The following product (including the customer specific product)**

- All the products of MFSOP and SO-XX type, using tape and reel packaging:  
 Please see the attachment for the detail.
- \* including the product manufactured by Toshiba Semiconductor (Thailand) (Abbreviation: (TST)).

**2. Description of change : The packing specification is changed as follows.**

Changes	Current	New
Outer carton box, and the quantity to be contained in its carton.	Containing 10 inner cartons. Inside dimension : 381×376×341mm Outside dimension : 391×386×356mm 	Containing 5 inner cartons. Inside dimension : 375×360×160mm Outside dimension : 385×370×175mm 

**3. Purpose of change**

- Reducing of vibration during transport.  
 \* The risk of deformation by vibration on an embossed tape and a lead of product will be reduced by the change.

**4. Product characteristics**

- Since the change is the quantity of inner carton to be packed, there is no change in the product structure and the process. Initial characteristics and reliability level will not change.

**5. Schedule of change**

- All the applicable product is planned to be changed from the production of March 2017.

**6. Request**

- Please inform us if you have any inconvenience on this change through our sales representatives by February 24, 2017.  
 If we have not heard from you by the date, we will assume that you have agreed to this change.

Sincerely yours,



\_\_\_\_\_  
 F. Hirano / Manager  
 Quality Planning Group  
 Quality Assurance Department  
 Buzen Toshiba Electronics Corporation

(Drafted by T. Uchino)